

# 30V P-Channel Trench MOSFET(Preliminary)

# **General Description**

- Trench Power technology
- Low R<sub>DS(ON)</sub>
- Low Gate Charge
- Optimized for fast-switching applications

### **Applications**

- Synchronous Rectification in DC/DC and AC/DC Converters
- Isolated DC/DC Converters in Telecom and Industrial

### **Product Summary**

 $V_{DS}$  -30V

 $I_D$  (at  $V_{GS}$ =-10V) -20A

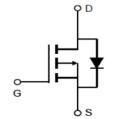
 $R_{DS(ON)}$  (at  $V_{GS}$  =-10V) < 17m $\Omega$ 

 $R_{DS(ON)}$  (at  $V_{GS}$  =-4.5V) < 30m $\Omega$ 



DFN3.3x3.3





Part Number	Package Type	Form	Marking	
TTG20P03ATC	DFN3.3x3.3	Tape & Reel	TTG20P03AT	

## Absolute Maximum Ratings (T<sub>A</sub> =25°C unless otherwise noted)

Parameter		Symbol	Maximum	Units
Drain-Source Voltage		V <sub>DS</sub>	-30	V
Gate-Source Voltage		V <sub>GS</sub>	±20	V
Continuous Drain Current B	T <sub>C</sub> =25°C	I <sub>D</sub>	-17	Δ
	T <sub>C</sub> =100°C		-13	А
Pulsed Drain Current A		I <sub>DM</sub>	-80	А
Avalanche Current <sup>A</sup>		I <sub>AS</sub>	22	A
Single Pulse Avalanche Energy L =0.3mH A		E <sub>AS</sub>	72.6	mJ
Power Dissipation <sup>C</sup>	T <sub>C</sub> =25°C	- P <sub>D</sub>	11.3	W
	T <sub>C</sub> =100°C		4.5	W
Junction and Storage Temperature Range		$T_J$ , $T_{STG}$	-55 to 150	°C
Thermal Characteristics				

#### Thermal Characteristics

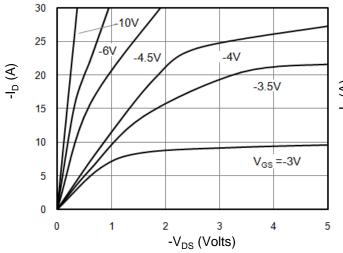
Parameter		Symbol	Maximum	Units
Maximum Junction-to-Case	Steady-State	$R_{\Theta JC}$	11	00.004
Maximum Junction-to-Ambient	Steady-State	$R_{\Theta JA}$	100	°C/W



Electric	cal Characteristics(T <sub>J</sub> =25°C ur	nless otherwise r	noted)				
Currele el	Devenuetos			Value			
Symbol	bol Parameter Conditions			Min	Тур	Max	Units
STATIC P	ARAMETERS						-
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$I_D = -250 \mu A, V_{GS} = 0 V$		-30			V
I <sub>DSS</sub> Zero Gate Voltaç		V <sub>DS</sub> =-30V, V <sub>GS</sub> =0V	T <sub>J</sub> =25°C			-1	μА
	Zero Gate Voltage Drain Current		T <sub>J</sub> =125°C			-100	
I <sub>GSS</sub>	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$				±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA		-1	-1.6	-2.4	V
		V <sub>GS</sub> =-10V, I <sub>D</sub> =-20A			14.5	17	mΩ
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-20A			23	30	mΩ
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =-5V, I <sub>D</sub> =-4A			21		S
V <sub>SD</sub>	Diode Forward Voltage	I <sub>S</sub> =-10A, V <sub>GS</sub> =0V				-1	V
I <sub>S</sub>	Maximum Body-Diode Continuous Curre	Maximum Body-Diode Continuous Current B				-17	Α
DYNAMIC	PARAMETERS						Į.
C <sub>iss</sub>	Input Capacitance	$V_{GS} = 0V$ , $V_{DS} = -15V$ , $f = 1MH_Z$ $f = 1MH_Z$			1973		pF
C <sub>oss</sub>	Output Capacitance				222		
C <sub>rss</sub>	Reverse Transfer Capacitance				195		
$R_g$	Gate Resistance				5.4		Ω
SWITCHIN	NG PARAMETERS	•					
Q <sub>g</sub> (10V)	Total Gate Charge				41		
Q <sub>g</sub> (4.5V)	Total Gate Charge	10)/// 15)/	1 204		20		nC
$Q_{gs}$	Gate Source Charge	$V_{GS} = -10V, V_{DS} = -15V, I_{D} = -20A$			9		, IIC
$Q_{gd}$	Gate Drain Charge				6		
t <sub>D(on)</sub>	Turn-On Delay Time	$V_{GS}$ =-10V, $V_{DS}$ =-15V, $I_{D}$ =-20A, $R_{G}$ =2.5 $\Omega$			9		
t <sub>r</sub>	Turn-On Rise Time				10		ns
t <sub>D(off)</sub>	Turn-Off Delay Time				50		
t <sub>f</sub>	Turn-Off Fall Time				20		
t <sub>rr</sub>	Body Diode Reverse Recovery Time	I <sub>F</sub> =-10A, di/dt =100A/μs			24		ns
Q <sub>rr</sub>	Body Diode Reverse Recovery Charge				16		nC

- A. Single pulse width limited by maximum junction temperature.
- B. The maximum current rating is package limited.
- C. The power dissipation  $P_D$  is based on  $T_{J(MAX)}$ =150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

#### TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS



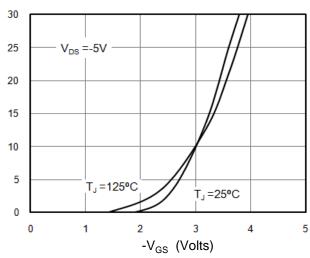


Figure 2: Transfer Characteristics

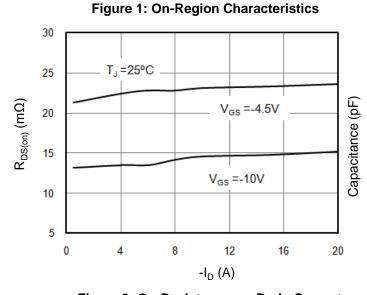


Figure 3: On-Resistance vs. Drain Current

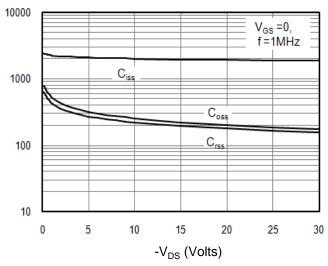
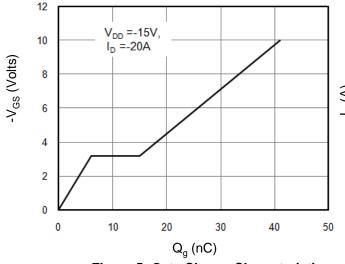


Figure 4: Capacitance Characteristics



**Figure 5: Gate Charge Characteristics** 

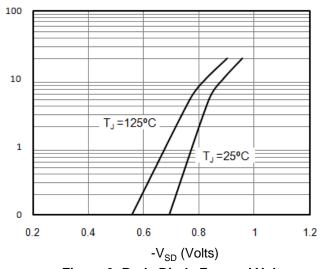
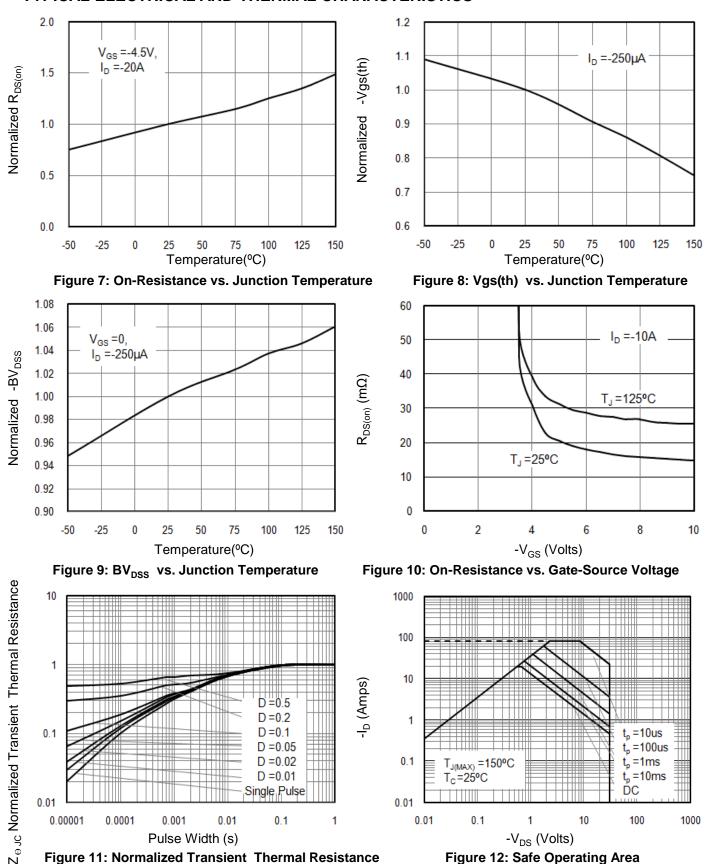


Figure 6: Body Diode Forward Voltage

Figure 12: Safe Operating Area

#### TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS



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Figure 11: Normalized Transient Thermal Resistance

Figure A: Gate Charge Test Circuit and Waveform

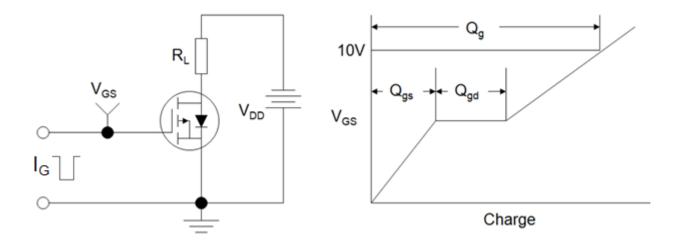


Figure B: Resistive Switching Test Circuit and Waveform

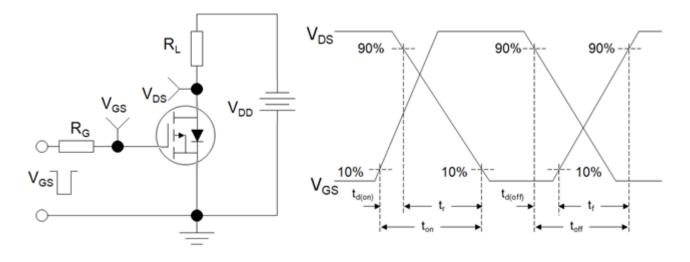
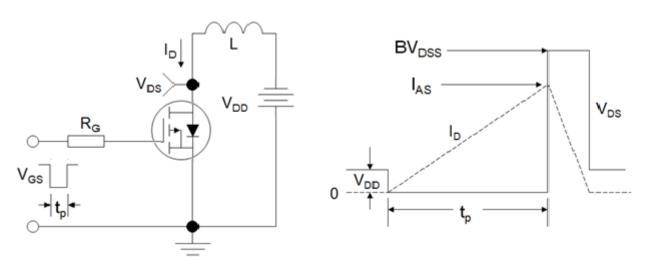
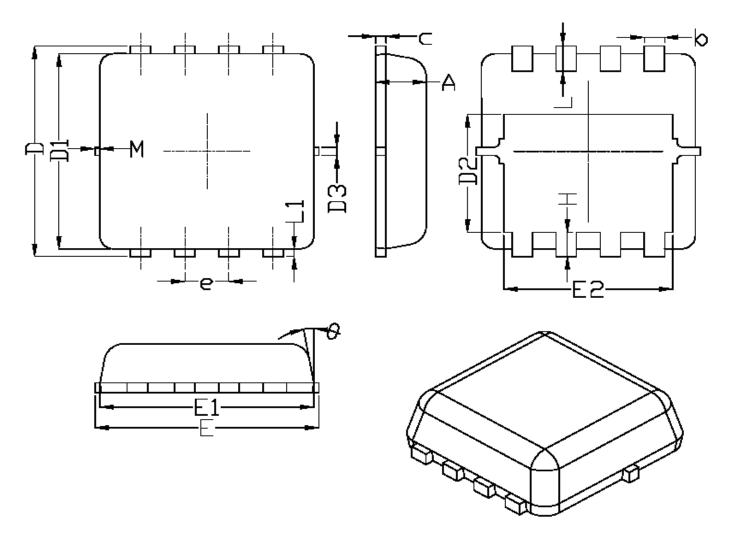


Figure C: Unclamped Inductive Switching Test Circuit and Waveform





# DFN3.3x3.3(捷敏)



DIMENSIONAL REQMTS				
SYMBOL	MIN	NOM	MAX	
A	0.70	0.75	0.80	
b	0.25	0.30	0.35	
С	0.10	0.15	0.25	
D	3.25	3.35	3.45	
D1	3.00	3.10	3.20	
D2	1.78	1.88	1.98	
D3		0.13		
E	3.20	3.30	3.40	
E1	3.00	3.15	3.20	
E2	2.39	2.49	2.59	
е	0.65BSC			
H	0.30	0.39	0.50	
L	0.30	0.40	0.50	
L1	0.13			
$\theta$		10°	12°	
M	*	* * 0.1		
* Not specified				



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